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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



XP04115

Silicon PNP epitaxial planar type

For digital circuits

■ Features

- Two elements incorporated into one package
(Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

- UNR2115 × 2

■ Package

- Code
SMini6-G1
- Pin Name

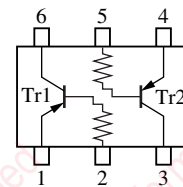
1: Emitter (Tr1)	4: Emitter (Tr2)
2: Base (Tr1)	5: Base (Tr2)
3: Collector (Tr2)	6: Collector (Tr1)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

	Parameter	Symbol	Rating	Unit
Rating of element	Collector-base voltage (Emitter open)	V_{CBO}	-50	V
	Collector-emitter voltage (Base open)	V_{CEO}	-50	V
	Collector current	I_{C}	-100	mA
Overall	Total power dissipation	P_{T}	150	mW
	Junction temperature	T_{j}	150	$^\circ\text{C}$
	Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Marking Symbol: 6T

■ Internal Connection

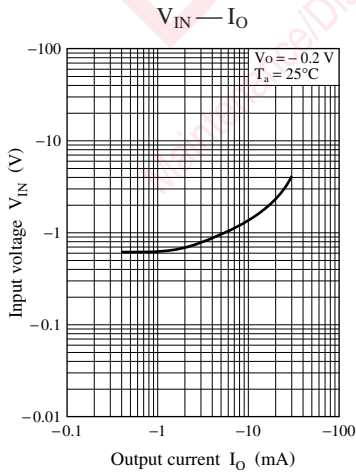
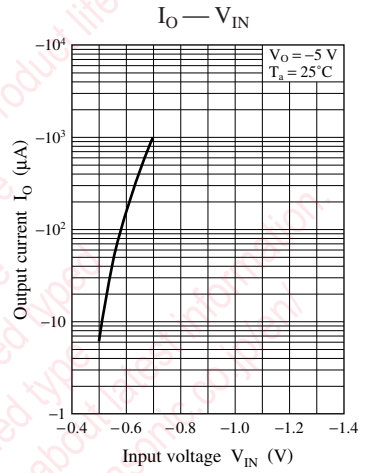
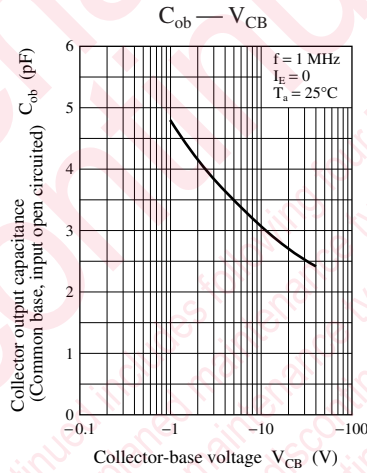
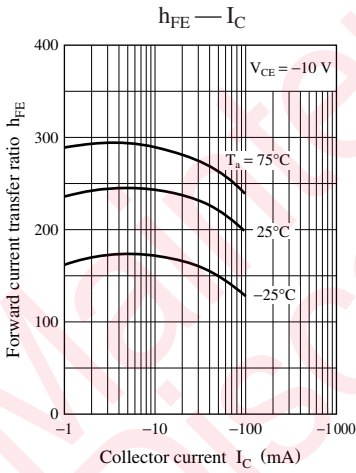
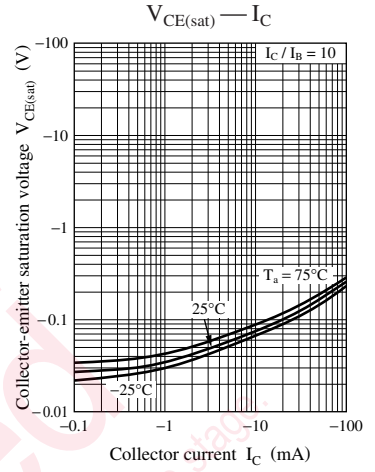
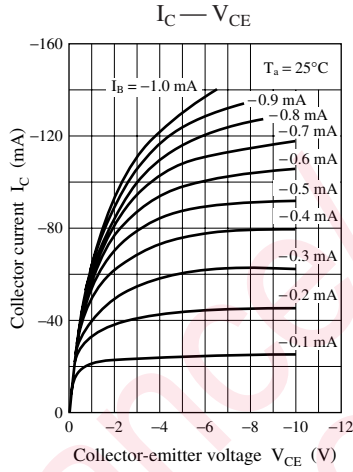
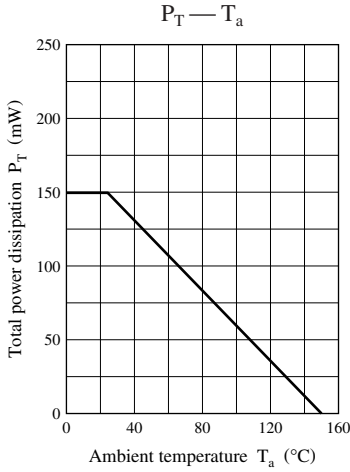


■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_{\text{C}} = -10 \mu\text{A}$, $I_{\text{E}} = 0$	-50			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_{\text{C}} = -2 \text{mA}$, $I_{\text{B}} = 0$	-50			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{\text{CB}} = -50 \text{V}$, $I_{\text{E}} = 0$			-0.1	μA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{\text{CE}} = -50 \text{V}$, $I_{\text{B}} = 0$			-0.5	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{\text{EB}} = -6 \text{V}$, $I_{\text{C}} = 0$			-0.01	mA
Forward current transfer ratio	h_{FE}	$V_{\text{CE}} = -10 \text{V}$, $I_{\text{C}} = -5 \text{mA}$	160		460	—
Collector-emitter saturation voltage	$V_{\text{CE(sat)}}$	$I_{\text{C}} = -10 \text{mA}$, $I_{\text{B}} = -0.3 \text{mA}$			-0.25	V
Output voltage high-level	V_{OH}	$V_{\text{CC}} = -5 \text{V}$, $V_{\text{B}} = -0.5 \text{V}$, $R_{\text{L}} = 1 \text{k}\Omega$	-4.9			V
Output voltage low-level	V_{OL}	$V_{\text{CC}} = -5 \text{V}$, $V_{\text{B}} = -2.5 \text{V}$, $R_{\text{L}} = 1 \text{k}\Omega$			-0.2	V
Input resistance	R_{I}		-30%	10	+30%	$\text{k}\Omega$
Transition frequency	f_{T}	$V_{\text{CB}} = -10 \text{V}$, $I_{\text{E}} = 1 \text{mA}$, $f = 200 \text{MHz}$		80		MHz

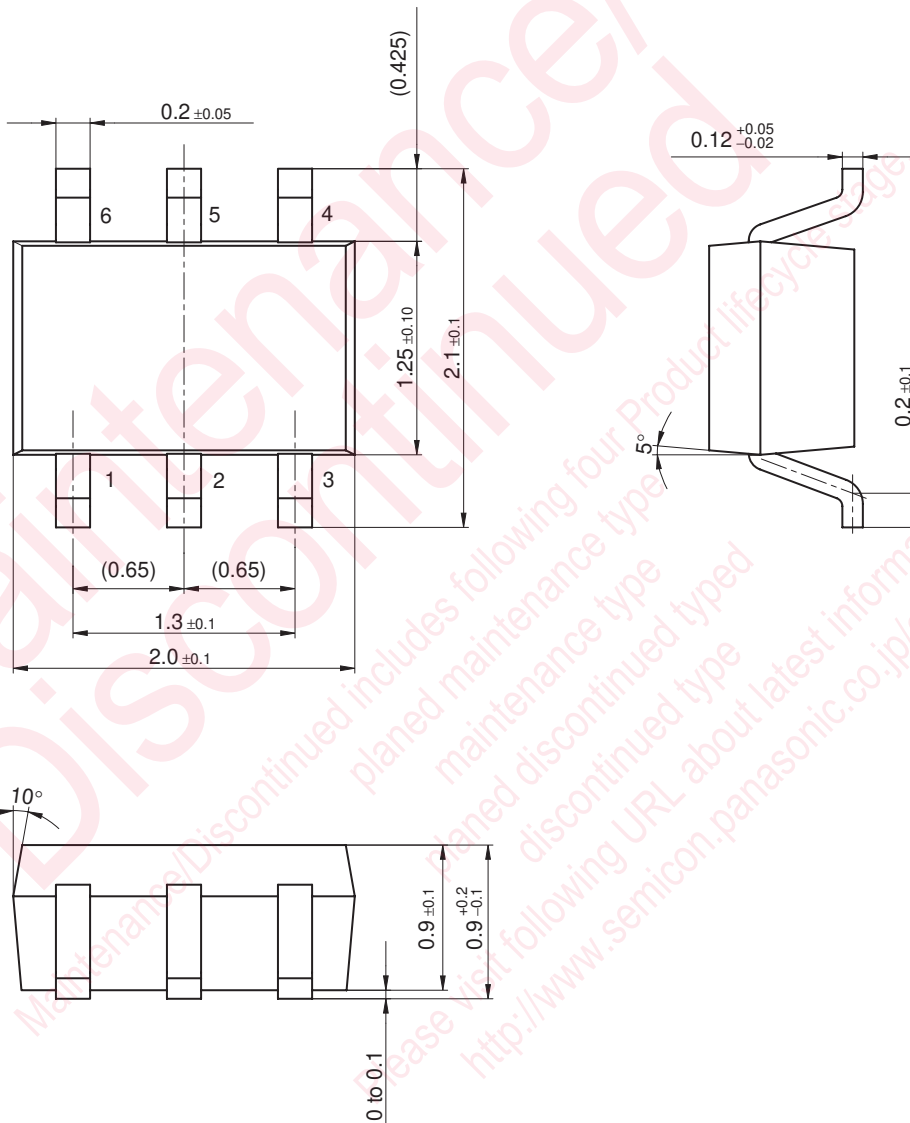
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

XP04115



SMini6-G1

Unit: mm



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